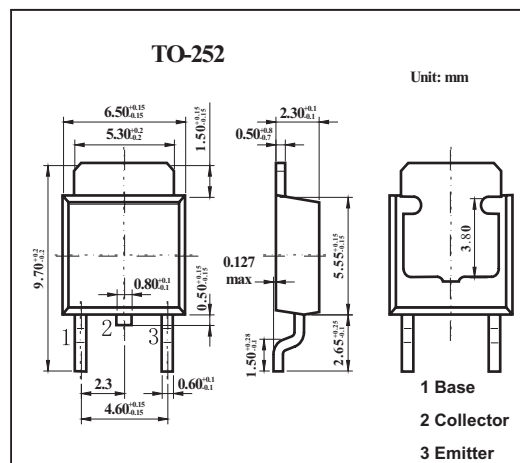


MJD44H11

■ Features

- Lead Formed for Surface Mount Applications in Plastic Sleeves
- Fast Switching Speeds
- Complementary Pairs Simplifies Designs
- Pb-Free Packages are Available



■ Absolute Maximum Ratings Ta = 25°C

Parameter	Symbol	Rating	Unit
Collector-emitter voltage	V _{CEO}	80	V
Emitter-base voltage	V _{EB}	5	V
Collector current	I _C	8	A
Collector current (pulse)	I _{CP}	16	A
Total Device Dissipation FR-5 Board @T _A = 25°C	P _D	20	W
Derate above 25°C		0.16	W/°C
Total Device Dissipation Alumina Substrate @T _A = 25°C	P _D	1.75	W
Derate above 25°C		0.014	W/°C
Junction temperature	T _j	150	°C
Storage temperature	T _{stg}	-55 to +150	°C
Thermal Resistance, Junction-to-Case	R _{θJC}	6.25	°C/W
Thermal Resistance, Junction-to-Ambient	R _{θJA}	71.4	°C/W
Lead Temperature for Soldering	T _L	260	°C

■ Electrical Characteristics Ta = 25°C

Parameter	Symbol	Testconditions	Min	Typ	Max	Unit
Collector-emitter sustaining voltage	VCEo(sus)	IC = 30 mA, IB = 0	80			V
Collector cutoff current	ICES	VCE = Rated VCEO, VEB = 0			10	μA
Emitter cutoff current	IEBO	VBE = 5V, IC = 0			50	μA
Collector-emitter saturation voltage	VCE(sat)	IC = 8 A, IB = 0.4 A			1	V
Base-emitter saturation voltage	VBE(sat)	IC = 8 A, IB = 0.8 A			1.5	V
DC current gain	HFE	IC = 2 A, VCE = 1 V	60			
		IC = 4 A, VCE = 1 V	40			
Collector capacitance	Ccb	VCB = 10 V, ftest = 1 MHz		130		pF
Current-gain-bandwidth product *2	fT	IC = 0.5 A, VCE = 10 V, f = 20 MHz		50		MHz
Delay and rise times	td + tr	IC = 5 A, IB1 = 0.5 A		300		ns
Storage time	ts	IC = 5 A, IB1 = IB2 = 0.5 A		500		ns
Fall time	tf	IC = 5 A, IB1 = IB2 = 0.5 A		140		ns

■ Marking

Marking	J44H11
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